

# HD74HCT540, HD74HCT541

## Octal Buffers/Line Drivers (with 3-state outputs)

REJ03D0668–0200  
 (Previous ADE-205-558)  
 Rev.2.00  
 Mar 30, 2006

### Description

The HD74HCT540 is an inverting buffer and the HD74HCT541 is a non-inverting buffer. The 3-state control gate operates as a two-input NOR such that if either  $\overline{G}_1$  or  $\overline{G}_2$  are high, all eight outputs are in the high-impedance state.

### Features

- LSTTL Output Logic Level Compatibility as well as CMOS Output Compatibility
- High Speed Operation:  $t_{pd}$  (A to Y) = 12 ns typ ( $C_L = 50$  pF)
- High Output Current: Fanout of 15 LSTTL Loads
- Wide Operating Voltage:  $V_{CC} = 4.5$  to  $5.5$  V
- Low Input Current:  $1 \mu\text{A}$  max
- Low Quiescent Supply Current:  $I_{CC}$  (static) =  $4 \mu\text{A}$  max ( $T_a = 25^\circ\text{C}$ )
- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74HCT540P HD74HCT541P	DILP-20 pin	PRDP0020AC-B (DP-20NEV)	P	—
HD74HCT540FPEL HD74HCT541FPEL	SOP-20 pin (JEITA)	PRSP0020DD-B (FP-20DAV)	FP	EL (2,000 pcs/reel)
HD74HCT541RPEL	SOP-20 pin (JEDEC)	PRSP0020DC-A (FP-20DBV)	RP	EL (1,000 pcs/reel)
HD74HCT540TELL HD74HCT541TELL	TSSOP-20 pin	PTSP0020JB-A (TTP-20DAV)	T	ELL (2,000 pcs/reel)

Note: Please consult the sales office for the above package availability.

### Function Table

Inputs			Output Y	
$\overline{G}_1$	$\overline{G}_2$	A	HD74HCT540	HD74HCT541
L	L	L	H	L
L	L	H	L	H
H	X	X	Z	Z
X	H	X	Z	Z

H : high level

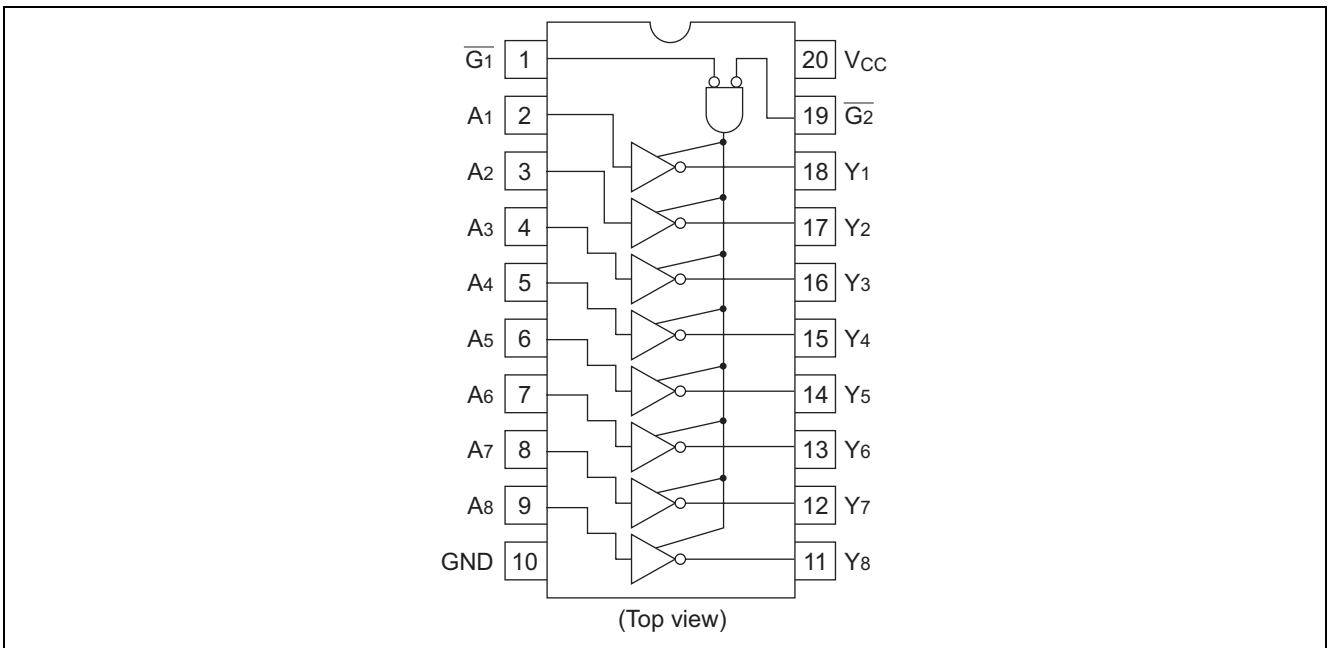
L : low level

X : irrelevant

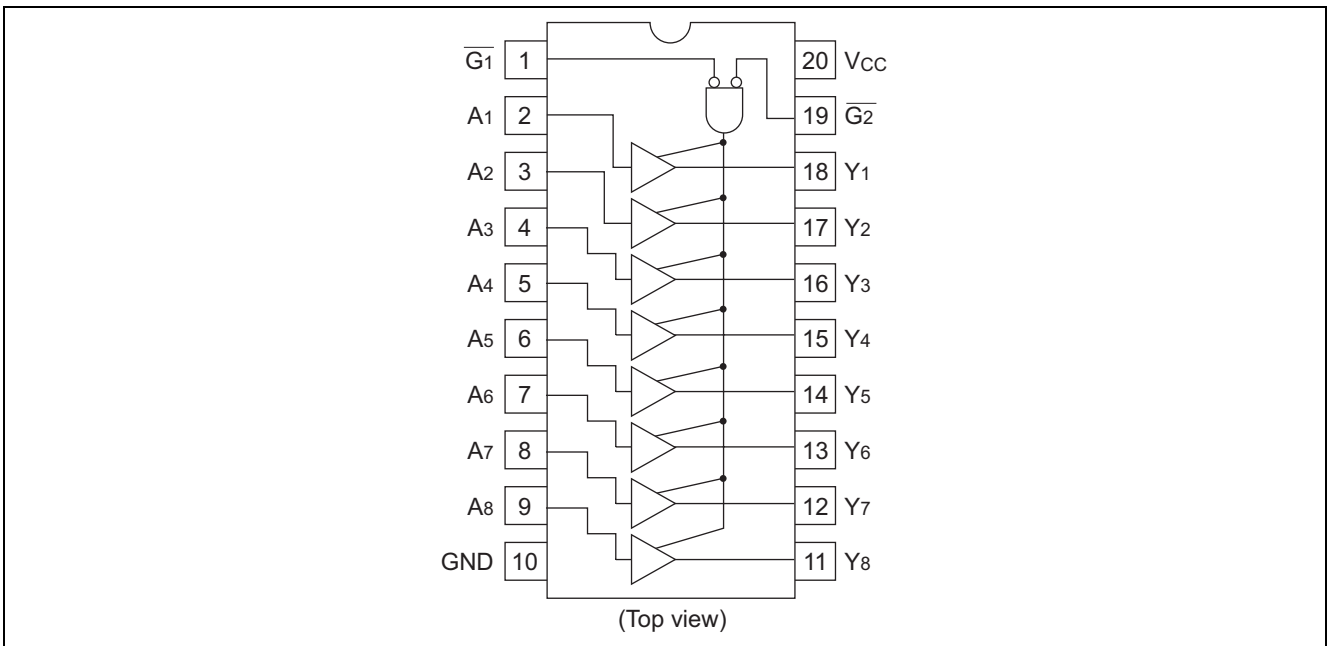
Z : off (high-impedance) state of a 3-state output

## Pin Arrangement

### HD74HCT540



### HD74HCT541



## Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage range	$V_{CC}$	-0.5 to 7.0	V
Input / Output voltage	$V_{IN}, V_{OUT}$	-0.5 to $V_{CC} + 0.5$	V
Input / Output diode current	$I_{IK}, I_{OK}$	$\pm 20$	mA
Output current	$I_O$	$\pm 35$	mA
$V_{CC}$ , GND current	$I_{CC}$ or $I_{GND}$	$\pm 75$	mA
Power dissipation	$P_T$	500	mW
Storage temperature	$T_{stg}$	-65 to +150	$^{\circ}C$

Note: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

## Recommended Operating Conditions

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	$V_{CC}$	4.5 to 5.5	V	
Input / Output voltage	$V_{IN}, V_{OUT}$	0 to $V_{CC}$	V	
Operating temperature	$T_a$	-40 to 85	$^{\circ}C$	
Input rise / fall time <sup>*1</sup>	$t_r, t_f$	0 to 500	ns	$V_{CC} = 4.5 V$

Notes: 1. This item guarantees maximum limit when one input switches.

Waveform: Refer to test circuit of switching characteristics.

## Electrical Characteristics

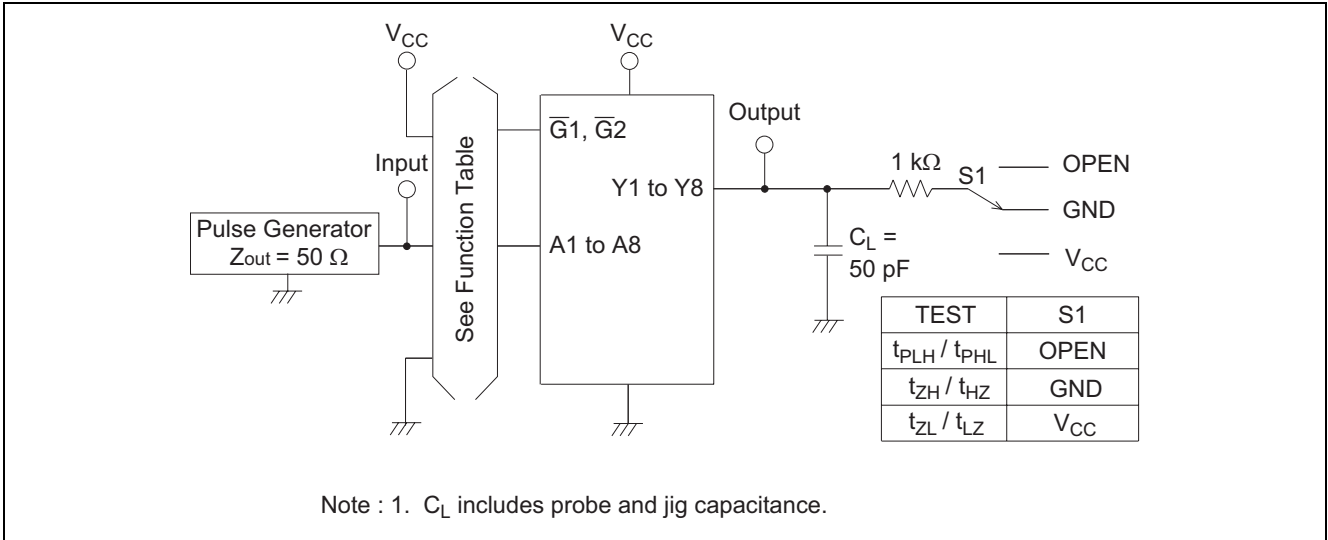
Item	Symbol	$V_{CC}$ (V)	$T_a = 25^{\circ}C$			$T_a = -40 \text{ to } +85^{\circ}C$		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Input voltage	$V_{IH}$	4.5 to 5.5	2.0	—	—	2.0	—	V		
	$V_{IL}$	4.5 to 5.5	—	—	0.8	—	0.8	V		
Output voltage	$V_{OH}$	4.5	4.4	—	—	4.4	—	V	$V_{in} = V_{IH}$ or $V_{IL}$	$I_{OH} = -20 \mu A$
		4.5	4.18	—	—	4.13	—	V		$I_{OH} = -6 \text{ mA}$
	$V_{OL}$	4.5	—	—	0.1	—	0.1	V	$V_{in} = V_{IH}$ or $V_{IL}$	$I_{OL} = 20 \mu A$
		4.5	—	—	0.26	—	0.33	V		$I_{OL} = 6 \text{ mA}$
Off-state output current	$I_{OZ}$	5.5	—	—	$\pm 0.5$	—	$\pm 5.0$	$\mu A$	$V_{in} = V_{IH}$ or $V_{IL}$ , $V_{out} = V_{CC}$ or GND	
Input current	$I_{in}$	5.5	—	—	$\pm 0.1$	—	$\pm 1.0$	$\mu A$	$V_{in} = V_{CC}$ or GND	
Quiescent current	$I_{CC}$	5.5	—	—	4.0	—	40	$\mu A$	$V_{in} = V_{CC}$ or GND, $I_{out} = 0 \mu A$	

## Switching Characteristics

( $C_L = 50 \text{ pF}$ , Input  $t_r = t_f = 6 \text{ ns}$ )

Item	Symbol	$V_{CC}$ (V)	$T_a = 25^{\circ}C$			$T_a = -40 \text{ to } +85^{\circ}C$		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Propagation delay time	$t_{PLH}$	4.5	—	11	20	—	25	ns	HD74HCT540 only	
	$t_{PHL}$	4.5	—	12	20	—	25			
	$t_{PLH}$	4.5	—	10	23	—	29	ns	HD74HCT541 only	
	$t_{PHL}$	4.5	—	13	23	—	29			
Output enable time	$t_{ZL}$	4.5	—	16	30	—	38	ns		
	$t_{ZH}$	4.5	—	20	30	—	38			
Output disable time	$t_{LZ}$	4.5	—	15	30	—	38	ns		
	$t_{HZ}$	4.5	—	15	30	—	38			
Output rise/fall time	$t_{TLH}$	4.5	—	4	12	—	15	ns		
	$t_{THL}$	4.5	—	4	12	—	15			
Input capacitance	$C_{in}$	—	—	5	10	—	10	pF		

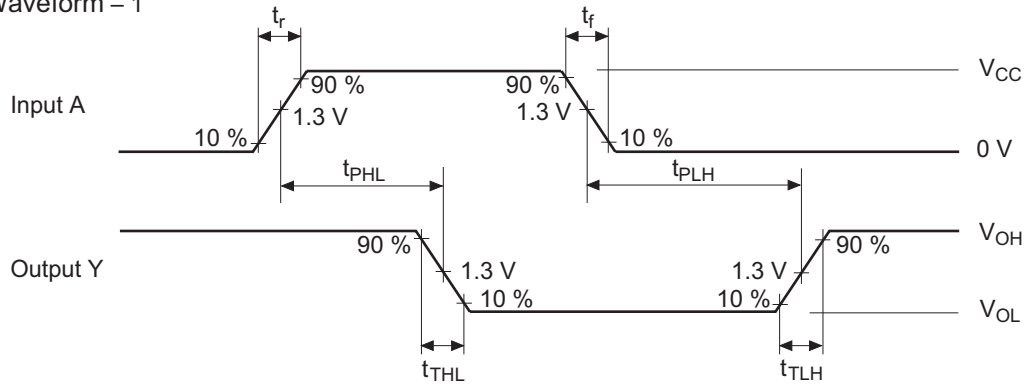
Test Circuit



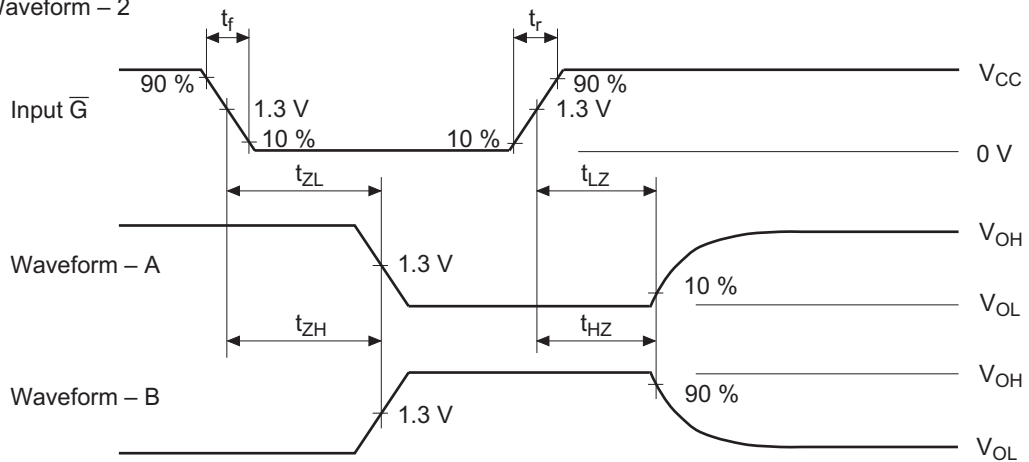
Waveforms

HD74HCT540

• Waveform – 1



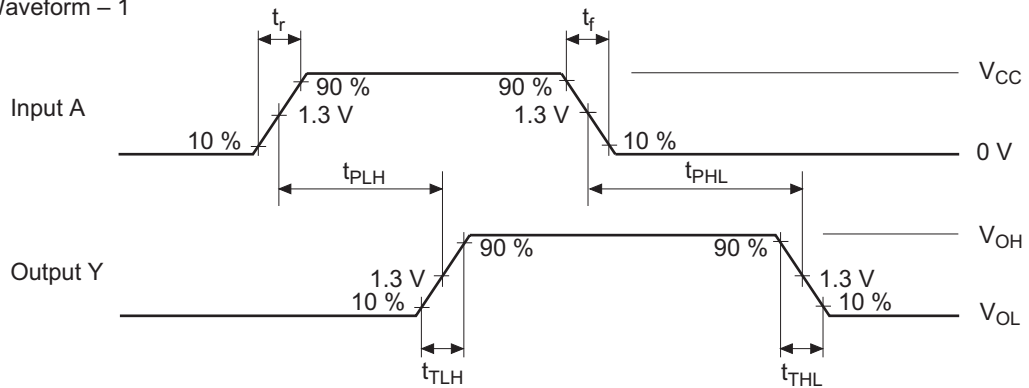
• Waveform – 2



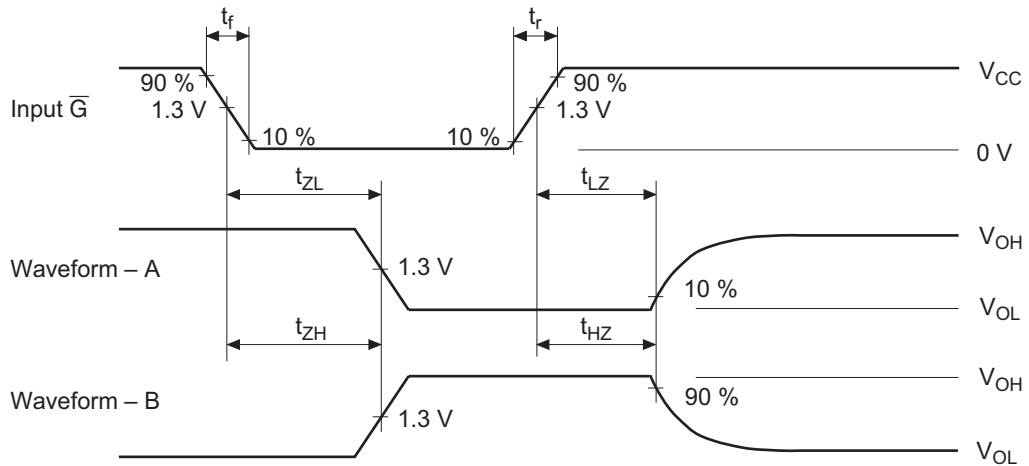
- Notes :
1. Input waveform :  $PRR \leq 1 \text{ MHz}$ , duty cycle 50%,  $t_r \leq 6 \text{ ns}$ ,  $t_f \leq 6 \text{ ns}$
  2. Waveform– A is for an output with internal conditions such that the output is low except when disabled by the output control.
  3. Waveform– B is for an output with internal conditions such that the output is high except when disabled by the output control.
  4. The output are measured one at a time with one transition per measurement.

HD74HCT541

• Waveform – 1

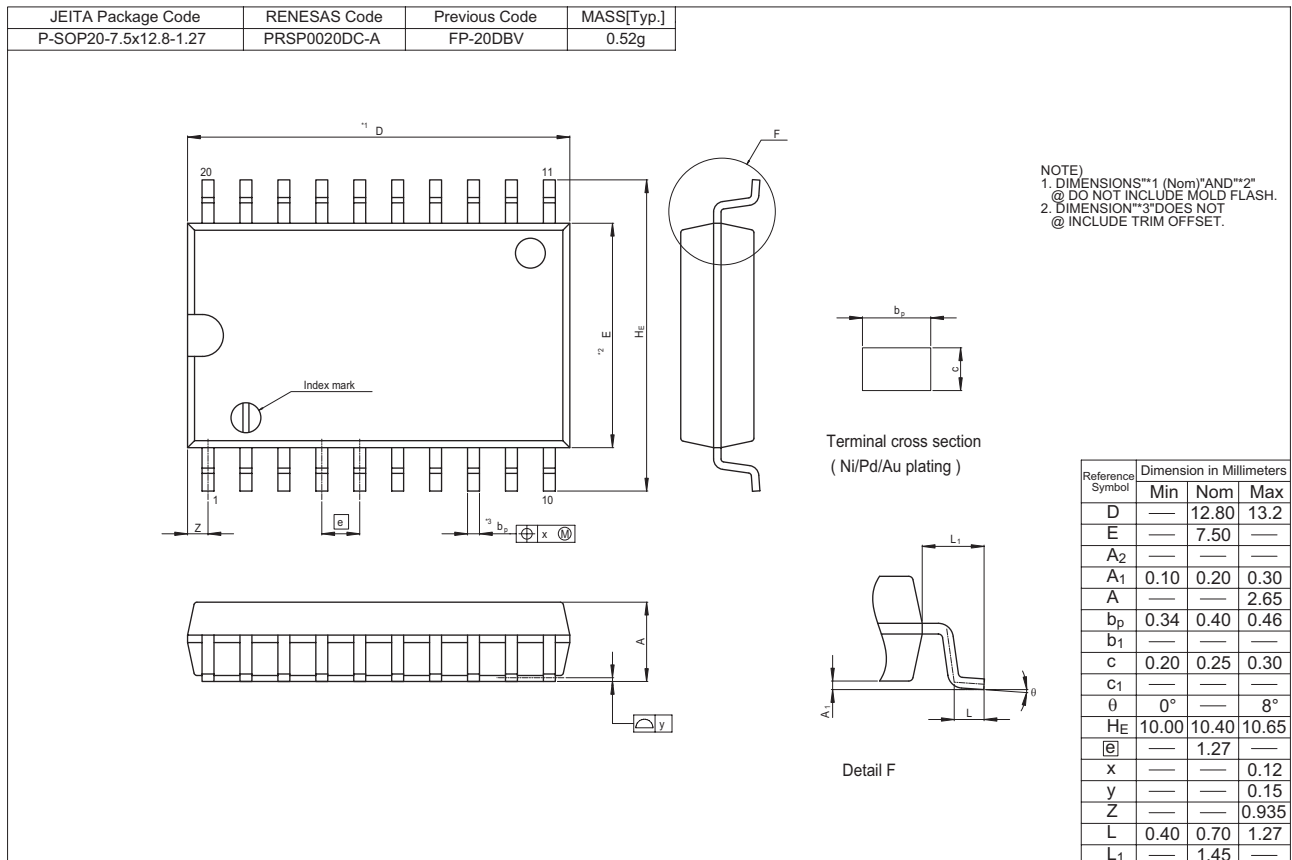
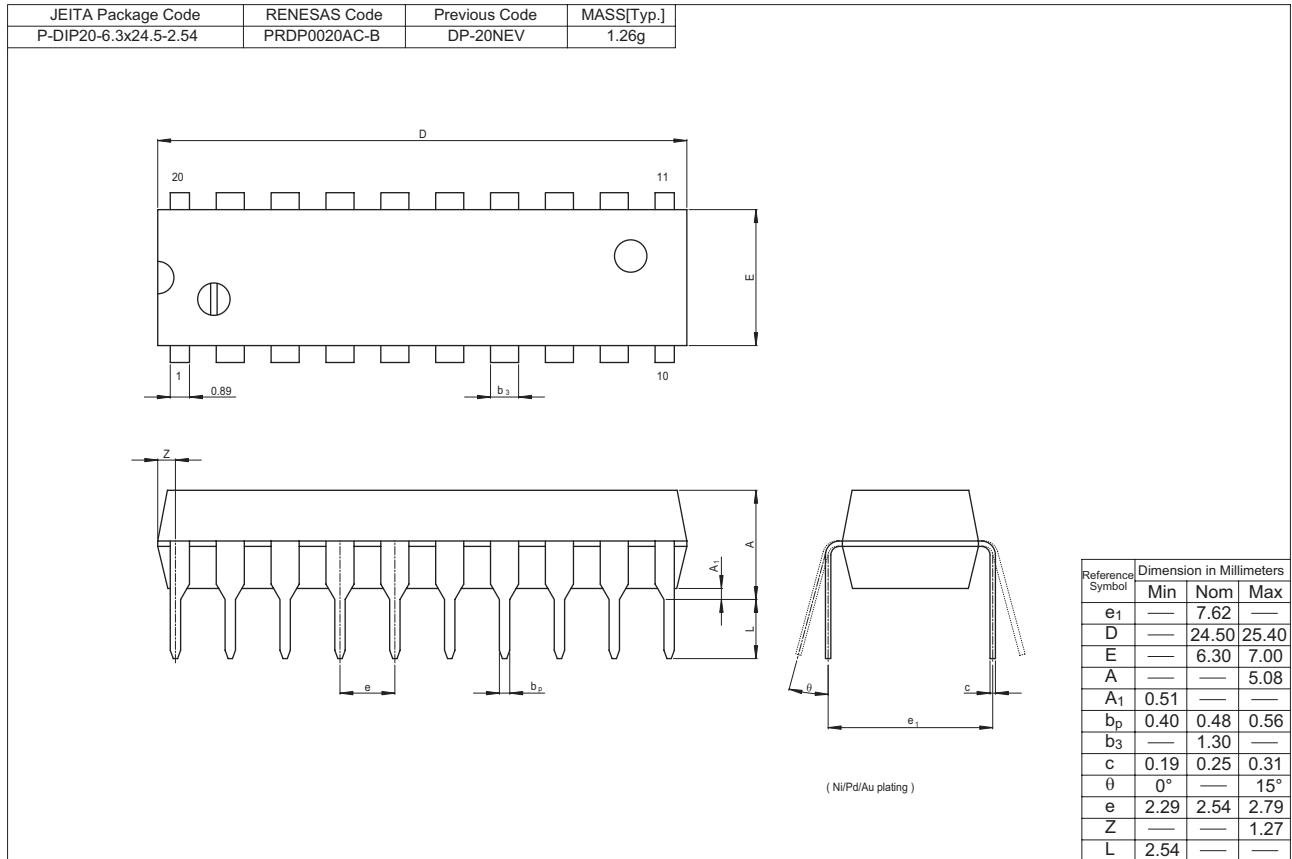


• Waveform – 2



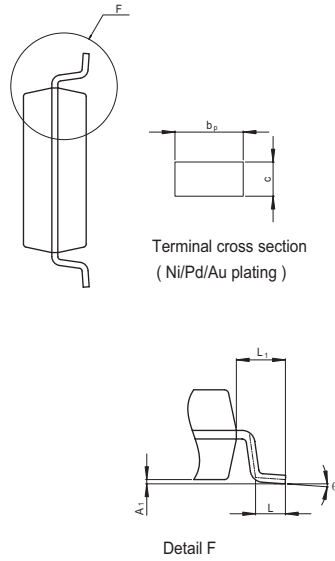
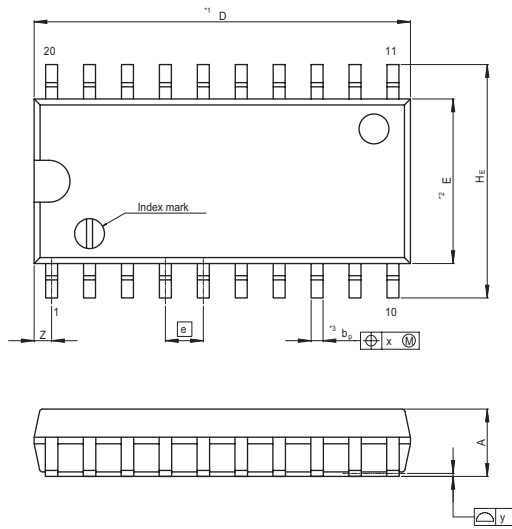
- Notes :
1. Input waveform : PRR  $\leq$  1 MHz, duty cycle 50%,  $t_r \leq$  6 ns,  $t_f \leq$  6 ns
  2. Waveform- A is for an output with internal conditions such that the output is low except when disabled by the output control.
  3. Waveform- B is for an output with internal conditions such that the output is high except when disabled by the output control.
  4. The output are measured one at a time with one transition per measurement.

Package Dimensions



# HD74HCT540, HD74HCT541

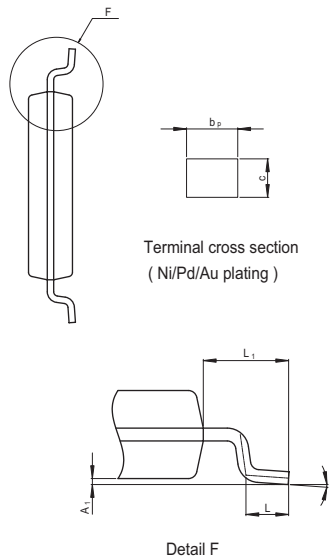
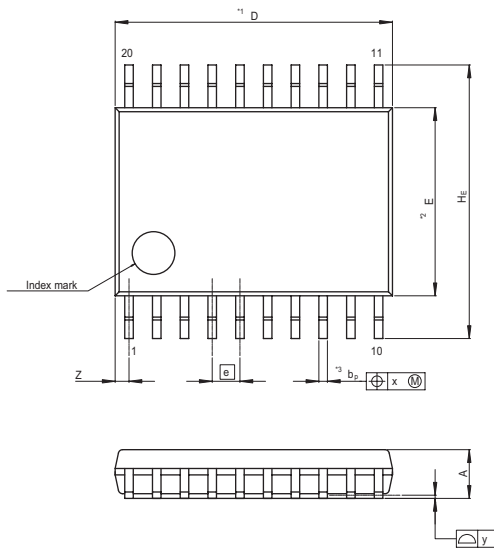
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SOP20-5.5x12.6-1.27	PRSP0020DD-B	FP-20DAV	0.31g



NOTE)  
 1. DIMENSIONS\*\*1 (Nom)\*\*AND\*\*2\*  
 DO NOT INCLUDE MOLD FLASH.  
 2. DIMENSION\*\*3\*DOES NOT  
 INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	12.60	13.0
E	—	5.50	—
A <sub>2</sub>	—	—	—
A <sub>1</sub>	0.00	0.10	0.20
A	—	—	2.20
b <sub>P</sub>	0.34	0.40	0.46
b <sub>1</sub>	—	—	—
c	0.15	0.20	0.25
c <sub>1</sub>	—	—	—
θ	0°	—	8°
H <sub>E</sub>	7.50	7.80	8.00
Ⓜ	—	1.27	—
x	—	—	0.12
y	—	—	0.15
Z	—	—	0.80
L	0.50	0.70	0.90
L <sub>1</sub>	—	1.15	—

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-TSSOP20-4.4x6.5-0.65	PTSP0020JB-A	TTP-20DAV	0.07g



NOTE)  
 1. DIMENSIONS\*\*1 (Nom)\*\*AND\*\*2\*  
 DO NOT INCLUDE MOLD FLASH.  
 2. DIMENSION\*\*3\*DOES NOT  
 INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	6.50	6.80
E	—	4.40	—
A <sub>2</sub>	—	—	—
A <sub>1</sub>	0.03	0.07	0.10
A	—	—	1.10
b <sub>P</sub>	0.15	0.20	0.25
b <sub>1</sub>	—	—	—
c	0.10	0.15	0.20
c <sub>1</sub>	—	—	—
θ	0°	—	8°
H <sub>E</sub>	6.20	6.40	6.60
Ⓜ	—	0.65	—
x	—	—	0.13
y	—	—	0.10
Z	—	—	0.65
L	0.4	0.5	0.6
L <sub>1</sub>	—	1.0	—



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**Renesas Technology America, Inc.**

450 Holger Way, San Jose, CA 95134-1368, U.S.A  
Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

**Renesas Technology Europe Limited**

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.  
Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

**Renesas Technology (Shanghai) Co., Ltd.**

Unit 204, 205, AZIACenter, No.1233 Lujiazui Ring Rd, Pudong District, Shanghai, China 200120  
Tel: <86> (21) 5877-1818, Fax: <86> (21) 6887-7898

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Tel: <852> 2265-6688, Fax: <852> 2730-6071

**Renesas Technology Taiwan Co., Ltd.**

10th Floor, No.99, Fushing North Road, Taipei, Taiwan  
Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

**Renesas Technology Singapore Pte. Ltd.**

1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632  
Tel: <65> 6213-0200, Fax: <65> 6278-8001

**Renesas Technology Korea Co., Ltd.**

Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea  
Tel: <82> (2) 796-3115, Fax: <82> (2) 796-2145

**Renesas Technology Malaysia Sdn. Bhd**

Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia  
Tel: <603> 7955-9390, Fax: <603> 7955-9510